

Technical Information Sheet

1. Name of technology	Recycling of precious metals contained in parts used in manufacturing equipment (semiconductors, LCDs, organic EL devices, and solar cells)
2. Type of technology	This technology enables the recycling of precious metals from parts for semiconductor production processes and others. Cleaning parts without damaging their base materials helps reduce the purchasing of new parts.
3. Description of technology	<p>[Objective and application of the technology] Precious metals such as gold and indium are used as wiring materials in such as semiconductor manufacturing processes. Our technology efficiently cleans these precious-metal adhering parts to enable the high-yield recycling of precious metals. Our precision cleaning process cleans the removed parts without damaging their base materials, thereby enabling their reuse, and maintains a high yield for our customers' manufacturing processes.</p> <p>Recycling procedure</p> <p>[Characteristics of the technology] (1) Recycles precious metals without damaging the base materials of parts (2) Removes fine deposits and metal constituents adhering to the surfaces of parts (low particle generation; low metal content)</p> <p>[Delivery record] Customers: Manufacturers of various devices such as semiconductors and FPDs</p> <p>[Price and other inquiries] Person in charge: Nobukiyo Konishi Planning and Sales Department, Semicon-Techno Business Division, Shinryo Corporation TEL: +81-93-643-2778 E-mail: 6008513@shinryo-gr.com</p>
4. Classification of technology	
(1) Applicable fields	Recycling (materials)
(2) Target waste	Electronic products
(3) Services provided	Other
5. Countries to which this technology can be provided	China, and Taiwan
6. Keywords	Precious metal, recycling, Wafer, reclamation, parts, cleaning, precision cleaning, recoating, surface treatment, thermal spray, alumite
7. Contact information	Please refer to [Price and other inquiries] under item 3.